Blue are new market stabilizing/positive leaning info. **Orange** are new neutral/negative info.

Device	Company	Production Profile	Comments
NAND	Overall NAND	NAND pricing surged 1H'26; supply constrained through 2027	
	Samsung	Vol.: 286L	- Annual licensing renewal required; 430L V10 expected to ramp in 2H'26 - Xi'an upgrade to V8/V9; P4 NAND delayed to 2026, prioritizing DRAM/HBM.
	Kioxia/Sandisk	Vol: 218L Ramp: 332L	- CapEx increase 41% YoY in '26 - BiCS10 332L pulled into 2026 to support AI, cloud & enterprise demand.
	SK Hynix	Vol.: 321L	- Volume production of 321L QLC V9, shifting >50% capacity to support SSD - Granted export licensing into China for 2026 & likely 2027.
	Micron	Vol.: 232L Vol: 276L	- Singapore 10B construction started, ramp in 2028, >2x capacity than 10A/X - Expected to accelerate NAND spend in 2027 but will lag DRAM.
	YMTC	Vol: 232/270L Ramp: 294L	- Started ramping 294L in '25; +15% capacity expansion targeted for E'26 - 3rd fab tool install ongoing, ramp to start in late'26; phase 4 & 5 in planning
DRAM	Overall DRAM	HBM driving expanded DRAM spend to support AI; $4F^2$ development in progress	
	Samsung	Vol: 1b nm, Vol.: 1c nm	- Accelerating P5 construction for expected mid-2027 ramp. - Migrating NAND capacity to DRAM, volume at 1c in 2026 (200kwspm).
	SK Hynix	Vol: 1b nm, Ramp: 1c nm	- Accelerating investment, adding >$15B CapEx annually through 2030. - Granted export licensing into China for 2026 & likely 2027. - M15X 1b production pulled into 1H'26, expanded construction start 1H'26
	Micron	Vol: 1β nm Ramp: 1γ nm	- Increased FY2026 CapEx to ~$27B,~$40B in 2027. - Groundbreaking on NY megafab complex ($100B), expected ramp 2030. - Japan fab announce expansion ($10B) into advanced DRAM, ramp 2H28. - PSMC P5 in Taiwan, Boise & Singapore assembly/test to ramp in 2027
	ChangXin Mem. Tech. (CXMT)	Vol: 1y Ramp: 1z	- Fab2 (Hefei) ramping; not on entities list but nearing BIS node limit - Expanding Shanghai capacity, tools in 2H'26 with E'26 ramp
	Other Memory	HBM 1x	- YMTC: new fab in Wuhan will have 50% dedicated to DRAM for HBM, 2027 - Nanya: updated 2026 CapEx to >$1.6B; announced 2027 4x CapEx increase - Winbond: accelerated Kaohsiung ramp of 16nm with tools moving in 2H26
Foundry/Logic	Foundry/Logic	Leading & trailing nodes investment planned. Advanced packaging is capacity limited.	
≤16nm	TSMC	3nm 2nm GAA	- FY'26 CapEx to ~$60-64B; indicated expansive spend increase to support AI/HPC - Total US investment $165B, potential additional $100B & acquired new site - AZ (Fab1 4nm, 2025; F2 3nm, 2026; F3 2nm, 2027), Japan fab2 (3nm, 2028)
≤16nm	Intel	4nm ≤14nm	- CapEx ~$20B; ~$6B Ireland investment; Ohio TBD - AZ 18A production ramping; announced partnership with TeraFab for 14A
≤16nm	Samsung	3nm GAA	- 2026 YoY CapEx +22%. Taylor TX planned ops E'26; 2nd Fab const. to start 'E'26. - Yongin complex pulled in 1-2 years, first fab 2029, 6 fabs by 2040 ($230B)
≤16nm	Rapidus	2nm GAA	- Production goal for 2027 accelerating ramp, $3-4B CapEx '25 → ~$8B 2026. - Announced new 1.4nm Hokkaido fab to start construction 2027.
≤16nm	GlobalFoundries	14nm	- Malta new fab planned, timing TBD.
≤16nm	SMIC	<14nm	- Target increase 5x 7nm/5nm output by 2028, affirming >$8B CapEx annually
≥20nm	TSMC	22/28nm 12/16nm	- Japan Fab 23 P2 considering migrating to more advanced nodes (3nm). - Dresden JV fab (target tool move-in 2H26, ramp 2H 2027-end);
≥20nm	UMC	28nm	- YoY CapEx +25%, announced new Tainan P7/8 fab and expanded Singapore P4
≥20nm	SMIC	28nm	- Continuing high spending with $8B+ forecast for 2026, Beijing fab start '2H26
≥20nm	Powerchip	>28nm	- Tongluo site acquired by Micron; Technology license sale to Tata (India) - Focus on advanced 3D integration from mature-nodes to support AI.
≥20nm	GlobalFoundries	28nm, FDSOI	- Dresden expansion expected 2028; Reiterated ST collaboration hold
≥20nm	Other	>28nm	- US: TI Reduced CapEx '26 to $2-3B, Sherman ahead of schedule. - China: CanSemi (Guangzhou, +40K wmp), Hua Hong (Wuxi, $6.7B +30K), Wingsky (Shanghai, 45K), Zensemi (MEMS, Quangshou), CR Micro (Shenzhen) - Japan: Toshiba (P2 '26), slowed/inactive: Renesas; Rohm, Sanken, Sony. - Europe: ST (Crolles on hold); Infineon (Dresden, 2026); India: Tata delay cont.
Packaging	TSMC	-	- $5-10B (10-15% CapEx), to support AI demand - US Adv. packaging fabs accelerating using P6 site, before 2029.
	Intel		- Consolidating sites (closing Costa Rica); canceled Poland plan (2027).
	GlobalFoundries		- Adding adv. pkg & test expansion to Malta
	SK Hynix		- HBM fab in Indiana (2028) and $13B site in Cheongju, expected ramp 2027.
	OSAT		- Starting capacity add for adv. Packaging; CoWoS pkg. bottleneck to persist to '28